

SEMICONDUCTOR



CMP PAD CONDITIONER

- **Application equipment:** AMAT(Mirra/Reflexion), Ebara(F-Rex200/300, EPO-222(H)), Lam(Auriga, CMP200/300, Avantgard 776(676), Momentum, Teres), Strasbaugh (6DS+SP, 6ED), etc.
- **Advantages:** Minimum defects and excellent uniformity of wafer equipped with precise diamond placement and protrusion control / Strong braze attachment offering superior diamond retention / World-class quality control and diamond selection controls.
- **应用设备:** AMAT(Mirra/Reflexion), Ebara(F-Rex200/300, EPO-222(H)), Lam(Auriga, CMP200/300, Avantgard 776(676), Momentum, Teres), Strasbaugh (6DS+SP, 6ED), etc.
- **特征:** 精密布局金刚石并对金刚石伸出进行控制从而使缺陷最小化以及晶片均匀性优秀 / 钎焊粘贴方式得到优秀的金刚石保持力 / 世界级品质管理以及金刚石选择



CVD CMP PAD CONDITIONER

- **Application equipment:** AMAT(Reflexion LK/Mirra), Ebara(F-REX series), K.C.T. etc.
- **Advantages:** Consistent pad cut rate and wafer removal rate for a longer period of time / Chemically intact (no metal contamination) / Low cost of consumables (disc & pad) and high-throughput through reduced PM time
- **应用设备:** AMAT(Reflexion LK/Mirra), Ebara(F-REX series), K.C.T. etc.
- **特征:** 抛光垫切割率以及晶片去除率可以连续更长一段时间 / 化学上完好(无金属污染) / 可降低消耗品成本(DISC & PAD) 以及高流通量减少PM时间

INNOVATOR IN TECHNOLOGY

EHWA DIAMOND



KOREA



CHINA / INDONESIA



GLOBAL BRANCHES



EHWA DIAMOND IND CO. LTD.

374, Nambudae-ro, Osan-city, Gyeonggi-do, 18145, Korea | semi@ehwadia.co.kr



Printed by Ehwa diamond / 2016. 01. 01

SINCE 1975

EHWA

Since 1975, EHWA has been able to greatly expand its market share throughout the world because we have established a world renowned reputation of high quality products, service and expertise in the industry. EHWA is deeply committed to keeping customers up-to-date and equipped with the most competitive products and technical information. Our success can only be measured by the success of our customers.

SEMICONDUCTOR
DISPLAY
SOLAR & LED



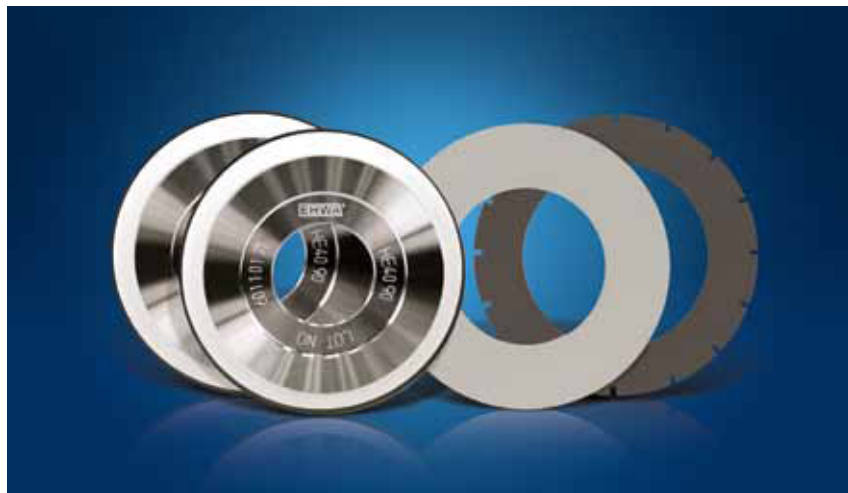
EHWA DIAMOND IND. CO. LTD.

SEMICONDUCTOR



BACK GRINDING WHEEL

- **Applications:** Silicon Wafer
- **Advantages:** Minimized wafer edge chipping / Improved die strength
Excellent grinding ability with high feed / Applicable thin wafer
- **产品应用:** 硅晶片
- **特征:** 晶片边缘碎屑最小化 / 芯片强度增加
在高进给速度优秀的切割能力 / 可适用于薄晶片



DICING & MICRO WHEEL

- **Applications:** Si wafer, Lt/LN wafer, glass wafer, ceramics, QFN, FBGA, CSP, MCP etc.
- **Advantages:** Minimized chipping size / High precision blade with superior cutting efficiency / Allowing for superior cutting quality at high RPM and fast feed rates
- **产品应用:** Si晶片, Lt/LN晶片, 玻璃片, 陶瓷, QFN, FBGA, CSP, MCP 等。
- **特征:** 碎屑最小化 / 优秀切割效率 / 在高RPM和进给可实现优秀的切割品质

DISPLAY



METAL EDGE GRINDING WHEEL

- **Application:** LCD panel, bare glass, sapphire and silicon wafer edge grinding
- **Advantages:** Allowing for high precision and a wide range of groove profiles / Uniform grinding ability with high edge strength / Double meshes for rough & fine grinding are applicable in one wheel
- **产品应用:** LCD 玻璃, 强化玻璃, 研磨硅晶片和蓝宝石晶片
- **特征:** 能实现高精密广泛的槽口形状 / 均一研磨品质和高边缘强度 / 能适用两种金刚石粒度(粗磨 & 细磨 同时适用)



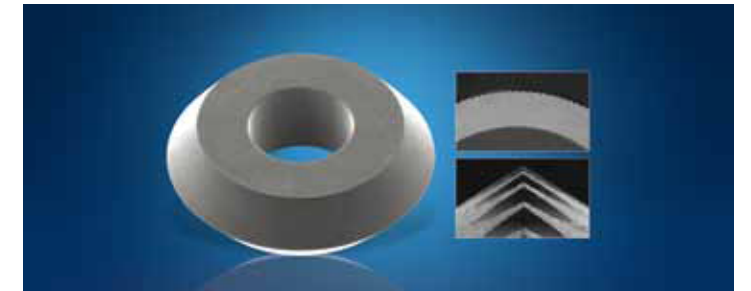
ELECTROPLATED EDGE GRINDING WHEEL

- **Applications:** Tempered glass for mobile, LCD panel, sapphire and silicon wafer edge grinding
- **Advantages:** Minimized product to product variation through stringent diamond grit distribution control / Superior cutting quality through optimized configuration of diamond grit size and concentration
- **产品应用:** 强化玻璃, LCD玻璃, 研磨硅晶片和蓝宝石晶片
- **特征:** 严格控制金刚石粒度减少品质偏差 / 通过金刚石粒度和集中的最佳配方得到优秀的切割效果



EDGE POLISHING WHEEL

- **Application:** LCD panel for mobile, OLED panel
- **Advantages:** Higher removal rate and Superior surface roughness (Stronger edge strength) / Longer life time
- **产品应用:** 手机用 LCD玻璃, OLED 玻璃
- **特征:** 优秀去除率和表面粗糙度(提高边缘强度) 长寿命



SCRIBING WHEEL

- **Application:** TFT-LCD PDP, TFT-LCD AMOLED, Touch sensor panel, OGS, etc.
- **Advantages:** Consistent product quality through automatic manufacturing system / Excellent glass edge strength (Minimized edge crack) / A wide range of applications
- **产品应用:** TFT-LCD PDP, TFT-LCD AMOLED, 电视屏幕, 强化玻璃等
- **特征:** 通过自动化系统达到品质稳定 / 优秀玻璃边缘强度(玻璃破损最小化) / 广泛的适用范围

SOLAR & LED



PDW (PRECISION DIAMOND WIRE)

- **Application:** Cropping – Mono silicon ingot, sapphire ingot
Squaring – Mono silicon ingot, poly silicon jumbo ingot
Slicing – Mono/poly silicon ingot wafer, sapphire wafer, silicon carbide (Sic) wafer
- **Advantages:** High throughput and superior cutting quality / Longer wire life time / Faster cutting speed
- **产品应用:** Cropping – 单晶硅锭, 蓝宝石锭 | Squaring – 单晶硅锭, 多晶放大硅锭 | Slicing – 单/多晶硅锭, 蓝宝石晶片, 碳化硅晶片
- **特征:** 优秀切割品质 / 长寿命 / 高切割速度



BACK GRINDING WHEEL (LED)

- **Applications:** Sapphire Wafer (LED)
- **Advantages:** Excellent grinding ability with high feed
Minimized wafer edge chipping / longer life time
- **产品应用:** 蓝宝石晶片 (LED)
- **特征:** 在高进给速度优秀的切割能力 / 晶片边缘碎屑最小化 / 长寿命